

APPLICATION DATA SHEET**Electronic Version v14****Stylesheet Version v14.0****Title of Invention****STACKED SEMICONDUCTOR PACKAGES AND METHOD FOR THE FABRICATION THEREOF****Application Type:** regular, utility**Attorney Docket Number:** 27-008**Correspondence address:****Customer Number:** 22898 ***22898*****Continuing Data:**

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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

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